

# LF 2012 Series (Preliminary)

Multilayer Chip Low-Pass Filters



## Features

❖ Ultra small SMD type with low loss at pass-band and high attenuation at stop-band.

## Applications

❖ 0.8-6GHz wireless communication systems, including DECT / PACS / PHS / GSM / DCS / PCS phones, WLAN card, Bluetooth modules, etc.

## Specifications

Part Number	Frequency Range (MHz)	Impedance (ohm)	Insertion Loss (dB)	Ripple (dB) @ BW	VSWR @ BW	Attenuation (dB)
<b>LF2012-E1R4DAA_</b>	500 ~ 2200	75	1.5 max.	0.3 max. over any 24MHz	2.0 max.	30.0 min. @ 2950 ~ 3300MHz

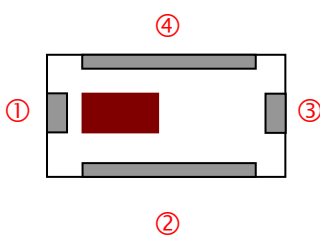
Q'ty/Reel (pcs) : 4,000  
 Operating Temperature Range : -40 ~ +85 °C  
 Storage Temperature Range : -40 ~ +85 °C  
 Storage Period : 12 months max.  
 Power Capacity : 1W max.

## Part Number

**LF**   **2012**   -   **E**   **1R4**   **DAA**   **□**   **/LF**  
 ①   ②   ③   ④   ⑤   ⑥   ⑦

① Type	LF : Low Pass Filter	② Dimensions ( L x W )	2.0 x 1.2 mm
③ Material Code	E	④ Frequency Range	1R4=1400MHz
⑤ Specification Code	DAA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	=lead-containing /LF=lead-free		

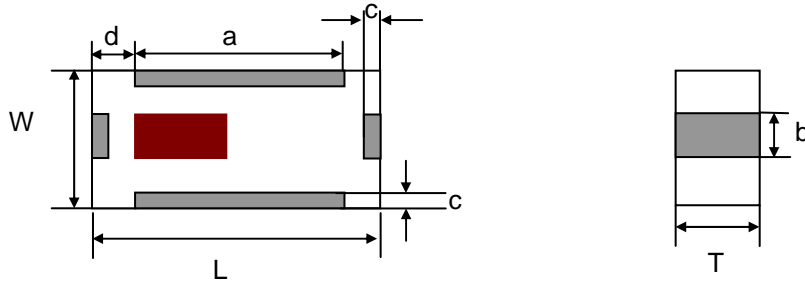
## Terminal Configuration



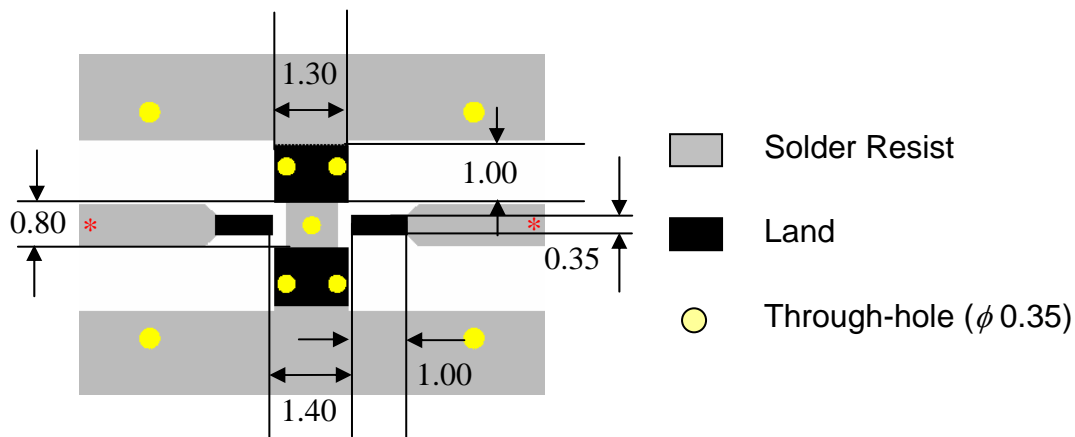
No.	Terminal Name	No.	Terminal Name
①	IN	③	OUT
②	GND	④	GND

**Dimensions and Recommended PC Board Pattern**

Unit : mm

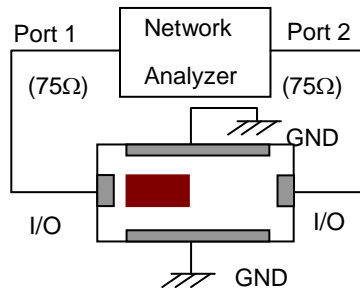


Mark	L	W	T	a	b	c	d
Dimensions	2.0 ±	1.25 ±	0.95±	1.3±	0.3 ±	0.25	0.35±
	0.15	0.10	0.10	0.15	0.15	+0.1/-0.15	0.15

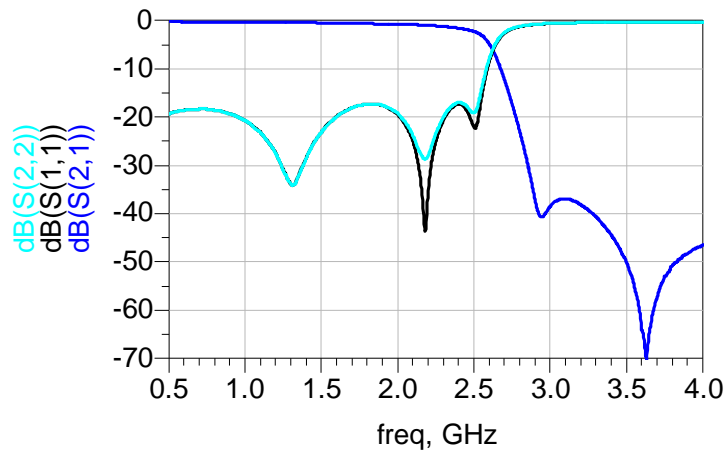


\* Line width should be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

## Measuring Diagram



## Typical Electrical Characteristics(T=25°C)

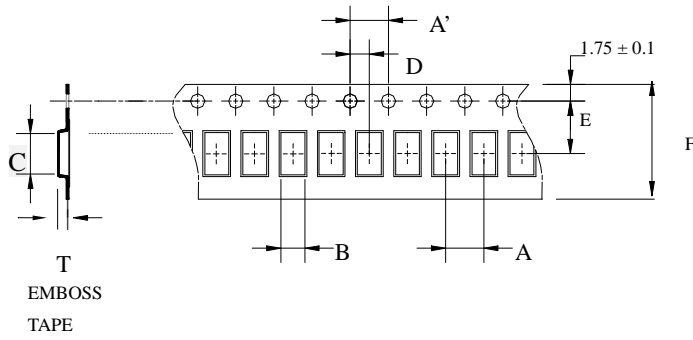


## Notes

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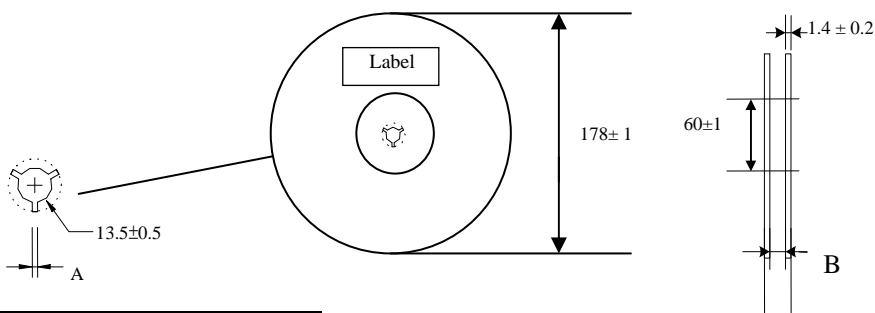
## Taping Specifications

### ❖Tape Dimensions (Unit: mm) & Quantity



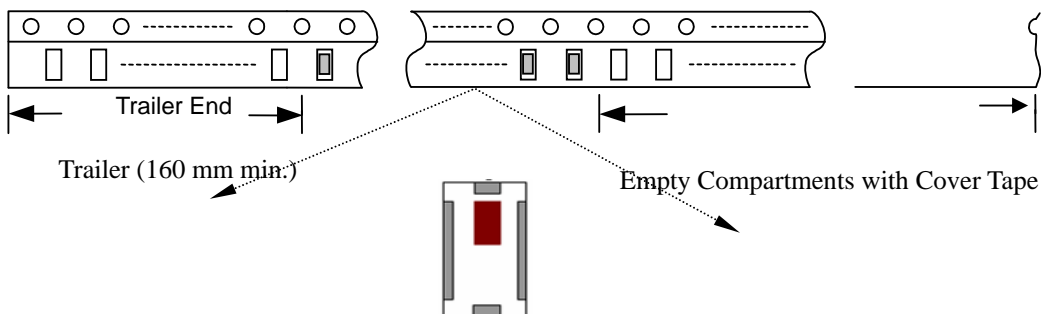
Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
2012	4.0±	4.0±	1.35±	2.15±	2.0±	3.5±	8.0±	1.08±	4,000pcs	Plastic (Embossed)
	0.1	0.1	0.05	0.05	0.05	0.1	0.1	0.05		

### ❖Reel Dimensions (Unit: mm)

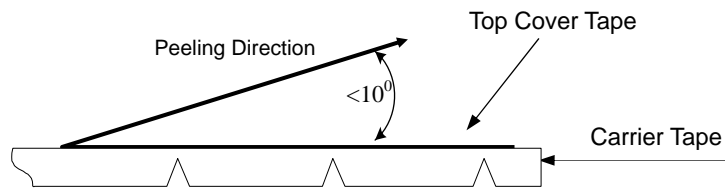


Type	A	B
2012	2.3±0.5	9.0±0.3

### ❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of  $300 \pm 10$  mm/min .

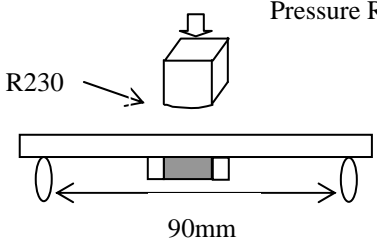
❖ **Storage Conditions**

- (1) Temperature:  $+5 \sim 35^{\circ}\text{C}$  , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment

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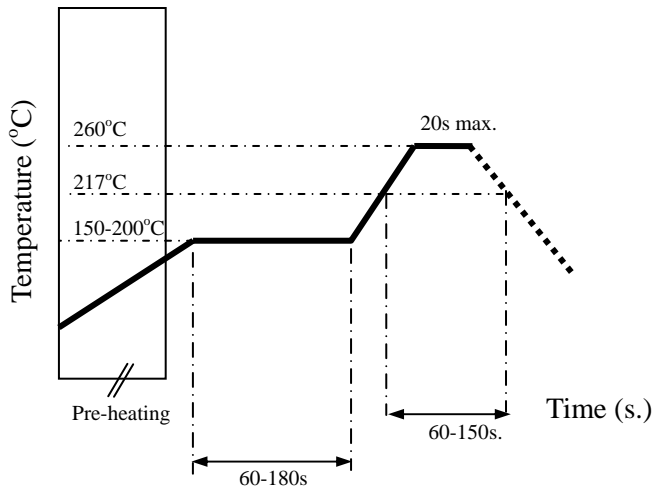
## Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>More than 95% of the terminal electrode shall be covered with new solder</li> </ol>	<ol style="list-style-type: none"> <li>Preheat: <math>120 \pm 5^\circ\text{C}</math></li> <li>Solder: <math>245 \pm 5^\circ\text{C}</math> for <math>5 \pm 1</math> sec</li> </ol>
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> <li>1kg minimum</li> </ol>	<ol style="list-style-type: none"> <li>Solder specimen onto test jig.</li> <li>Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction</li> </ol>
Deflection (Substrate Bending)	<ol style="list-style-type: none"> <li>No apparent damage</li> </ol>	<ol style="list-style-type: none"> <li>Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile.</li> <li>Apply a bending force of 2mm deflection</li> </ol> 
Heat/Humidity Resistance	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>Temperature: <math>85 \pm 2^\circ\text{C}</math></li> <li>Humidity: 90% ~ 95% RH</li> <li>Duration: <math>1000 \pm 48</math>hrs</li> <li>Recovery: 1-2hrs</li> </ol>
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>One cycle/step 1 : <math>125 \pm 5^\circ\text{C}</math> for 30 min step 2 : <math>-40 \pm 5^\circ\text{C}</math> for 30 min</li> <li>No of cycles : 100</li> <li>Recovery: 1-2 hrs</li> </ol>
Low Temperature Resistance	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>Temperature: <math>-40 \pm 5^\circ\text{C}</math></li> <li>Duration: <math>500 \pm 24</math>hrs</li> <li>Recovery: 1-2hrs</li> </ol>

## Soldering Conditions

### ❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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### Advanced Ceramic X Corp.

16 Tzu Chiang Road, Hsinchu Industrial District Hsinchu Hsien 303, Taiwan

TEL:886-3-5987008 FAX:886-3-5987001

E-mail: [acx@acxc.com.tw](mailto:acx@acxc.com.tw)

<http://www.acxc.com.tw>